

<For DTr1(NPN)>

Parameter	Value
$V_{CC}$	50V
$I_{C(MAX.)}$	100mA
$R_1$	10k $\Omega$
$R_2$	10k $\Omega$

<For DTr2(PNP)>

Parameter	Value
$V_{CC}$	-50V
$I_{C(MAX.)}$	-100mA
$R_1$	10k $\Omega$
$R_2$	10k $\Omega$

### ●Features

- 1)Both the DTA114E chip and DTC114E chip in a EMT or UMT or SMT package.
- 2)Mounting possible with EMT3 or UMT3 or SMT3 automatic mounting machines.
- 3)Transistor elements are independent, eliminating interference.
- 4)Mounting cost and area can be cut in half.

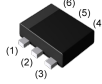
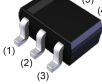
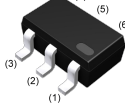
### ●Application

INVERTER, INTERFACE, DRIVER

### ●Packaging specifications

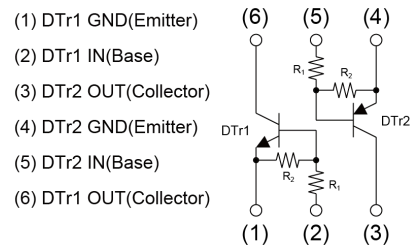
Part No.	Package	Package size	Taping code	Reel size (mm)	Tape width (mm)	Basic ordering unit.(pcs)	Marking
EMD3	SOT-563 (EMT6)	1616	T2R	180	8	8000	D3
UMD3N	SOT-363 (UMT6)	2021	TR	180	8	3000	D3
IMD3A	SOT-457 (SMT6)	2928	T108	180	8	3000	D3

### ●Outline

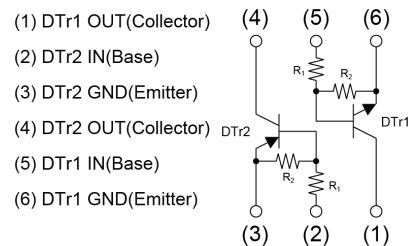
<p>SOT-563</p>  <p>EMD3 (EMT6)</p>	<p>SOT-363</p>  <p>UMD3N (UMT6)</p>
<p>SOT-457</p>  <p>IMD3A (SMT6)</p>	

### ●Inner circuit

EMD3 / UMD3N



IMD3A



**● Absolute maximum ratings ( $T_a = 25^\circ\text{C}$ )**

Parameter		Symbol	DTr1(NPN)	DTr2(PNP)	Unit
Supply voltage		$V_{CC}$	50	-50	V
Input voltage		$V_{IN}$	-10 to 40	-40 to 10	V
Output current		$I_O$	50	-50	mA
Collector current		$I_{C(MAX)}^{*1}$	100	-100	mA
Power dissipation	EMD3/ UMD3N	$P_D^{*2*3}$	150		mW/Total
	IMD3A	$P_D^{*2*4}$	300		
Junction temperature		$T_j$	150		$^\circ\text{C}$
Range of storage temperature		$T_{stg}$	-55 to +150		$^\circ\text{C}$

**● Electrical characteristics ( $T_a = 25^\circ\text{C}$ ) <For DTr1(NPN)>**

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Input voltage	$V_{I(off)}$	$V_{CC} = 5V, I_O = 100\mu\text{A}$	-	-	0.5	V
	$V_{I(on)}$	$V_O = 0.3V, I_O = 10\text{mA}$	3.0	-	-	
Output voltage	$V_{O(on)}$	$I_O = 10\text{mA}, I_I = 0.5\text{mA}$	-	100	300	mV
Input current	$I_I$	$V_I = 5V$	-	-	880	$\mu\text{A}$
Output current	$I_{O(off)}$	$V_{CC} = 50V, V_I = 0V$	-	-	500	nA
DC current gain	$G_I$	$V_O = 5V, I_O = 5\text{mA}$	30	-	-	-
Input resistance	$R_1$	-	7	10	13	k $\Omega$
Resistance ratio	$R_2/R_1$	-	0.8	1.0	1.2	-
Transition frequency	$f_T^{*1}$	$V_{CE} = 10V, I_E = -5\text{mA}, f = 100\text{MHz}$	-	250	-	MHz

**● Electrical characteristics ( $T_a = 25^\circ\text{C}$ ) <For DTr2(PNP)>**

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Input voltage	$V_{I(off)}$	$V_{CC} = -5V, I_O = -100\mu\text{A}$	-	-	-0.5	V
	$V_{I(on)}$	$V_O = -0.3V, I_O = -10\text{mA}$	-3.0	-	-	
Output voltage	$V_{O(on)}$	$I_O = -10\text{mA}, I_I = -0.5\text{mA}$	-	-100	-300	mV
Input current	$I_I$	$V_I = -5V$	-	-	-880	$\mu\text{A}$
Output current	$I_{O(off)}$	$V_{CC} = -50V, V_I = 0V$	-	-	-500	nA
DC current gain	$G_I$	$V_O = -5V, I_O = -5\text{mA}$	30	-	-	-
Input resistance	$R_1$	-	7	10	13	k $\Omega$
Resistance ratio	$R_2/R_1$	-	0.8	1.0	1.2	-
Transition frequency	$f_T^{*1}$	$V_{CE} = -10V, I_E = 5\text{mA}, f = 100\text{MHz}$	-	250	-	MHz

\*1 Characteristics of built-in transistor

\*2 Each terminal mounted on a reference land

\*3 120mW per element must not be exceeded.

\*4 200mW per element must not be exceeded.

● Electrical characteristic curves ( $T_a = 25^\circ\text{C}$ ) <For DTR1(NPN)>

Fig.1 Input Voltage vs. Output Current (ON Characteristics)

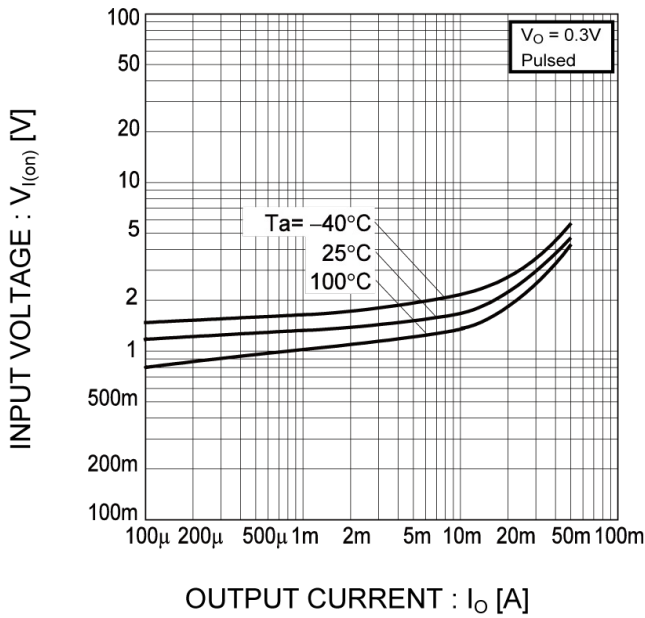


Fig.2 Output Current vs. Input Voltage (OFF Characteristics)

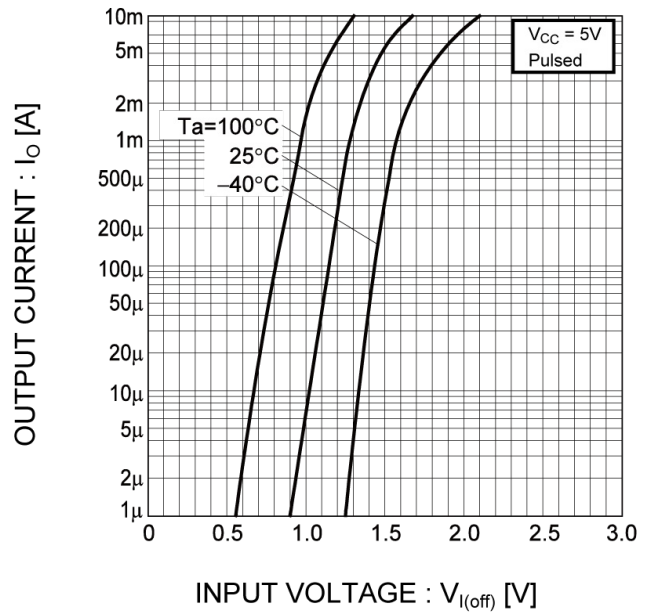


Fig.3 Output Current vs. Output Voltage

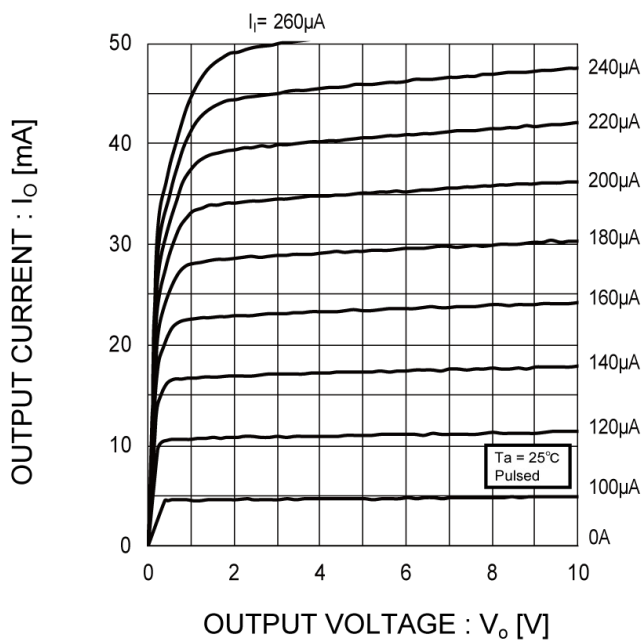
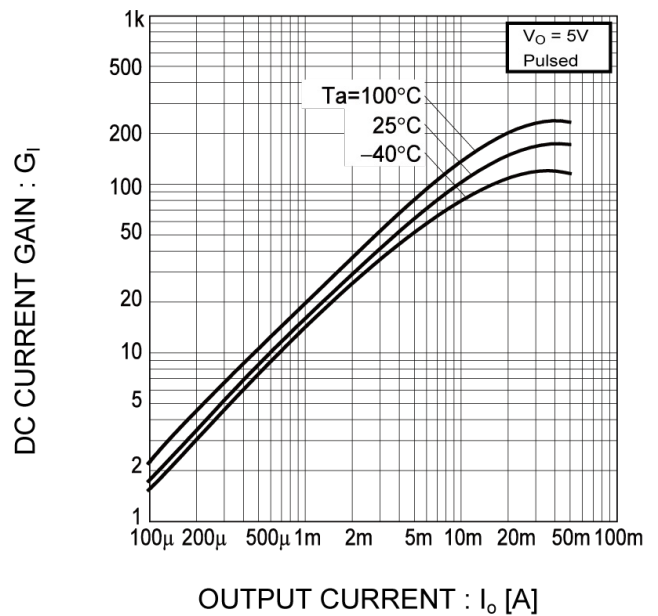
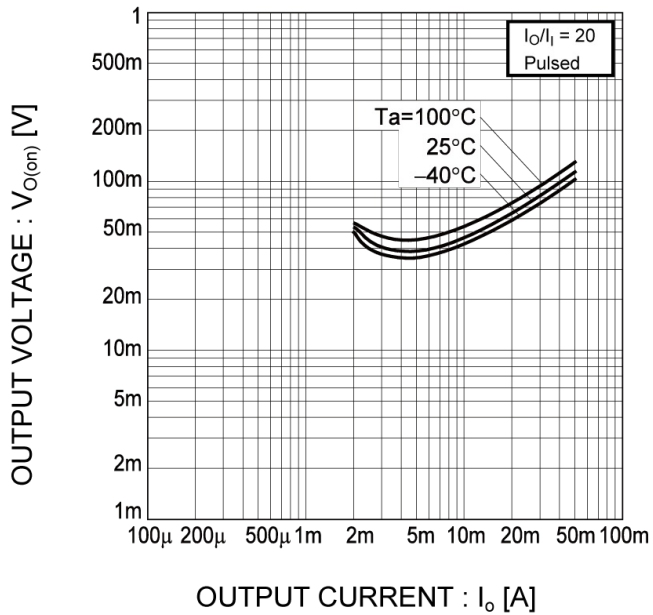


Fig.4 DC Current Gain vs. Output Current



● Electrical characteristic curves ( $T_a = 25^\circ\text{C}$ ) <For DTR1(NPN)>

Fig.5 Output Voltage vs. Output Current



●Electrical characteristic curves( $T_a=25^{\circ}\text{C}$ ) <For DTr2(PNP)>

Fig.1 Input Voltage vs. Output Current (ON Characteristics)

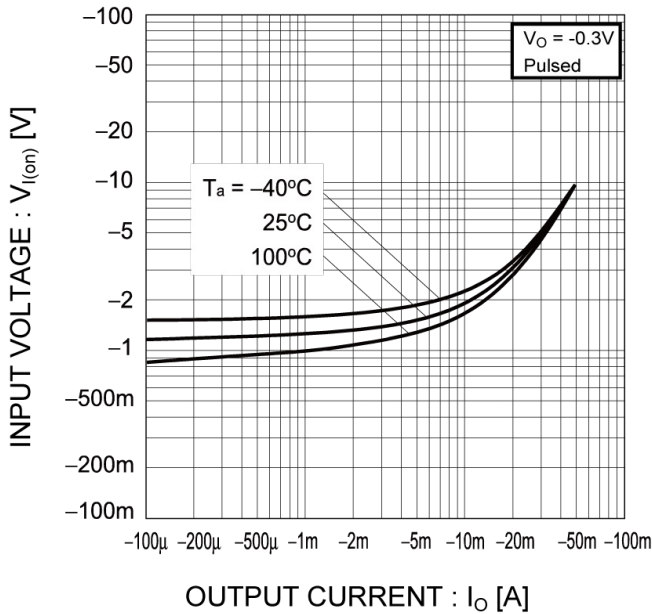


Fig.2 Output Current vs. Input Voltage (OFF Characteristics)

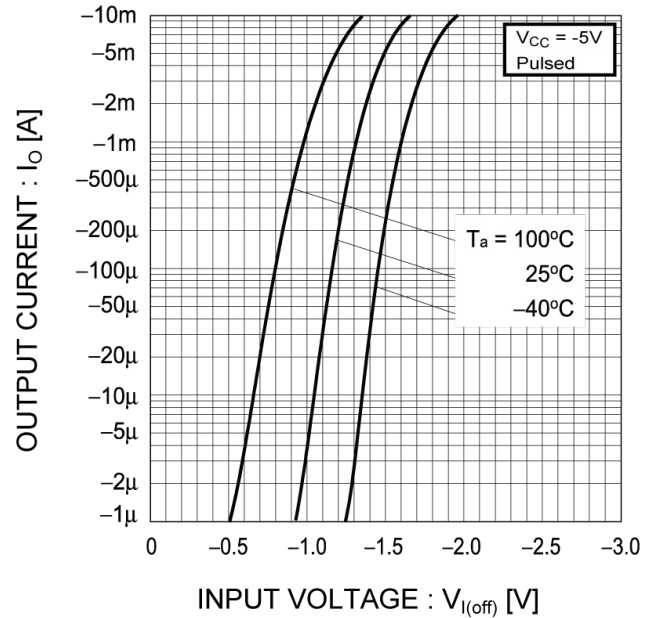


Fig.3 Output Current vs. Output Voltage

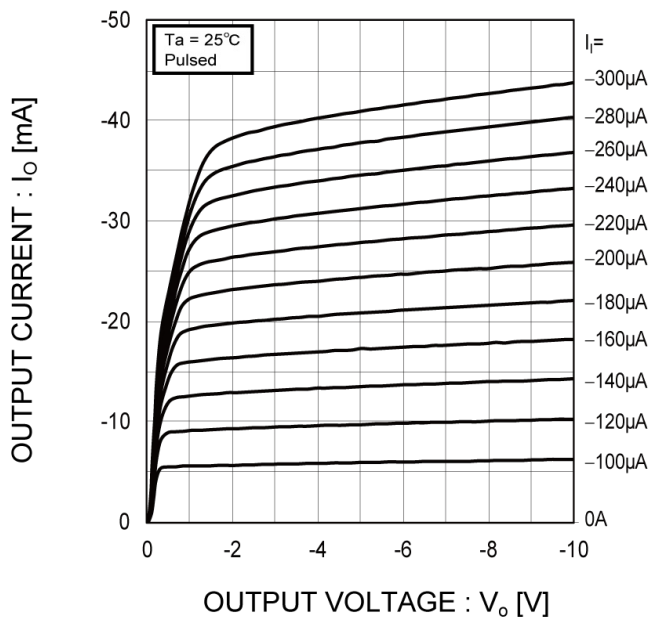
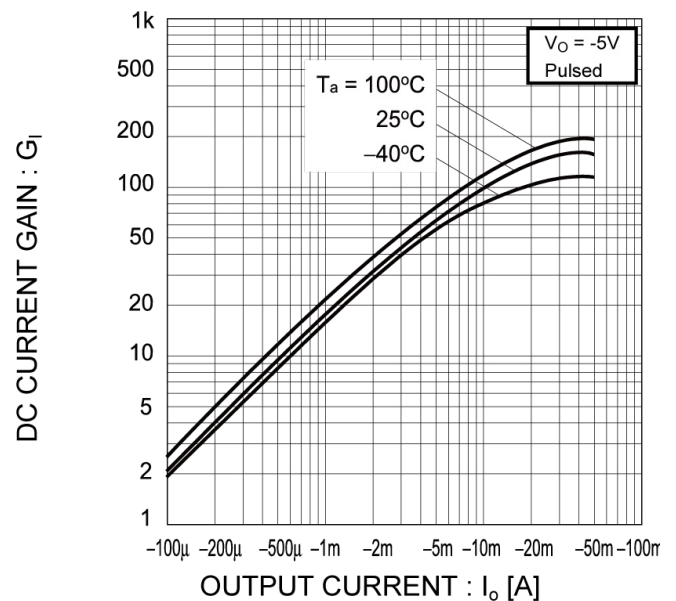
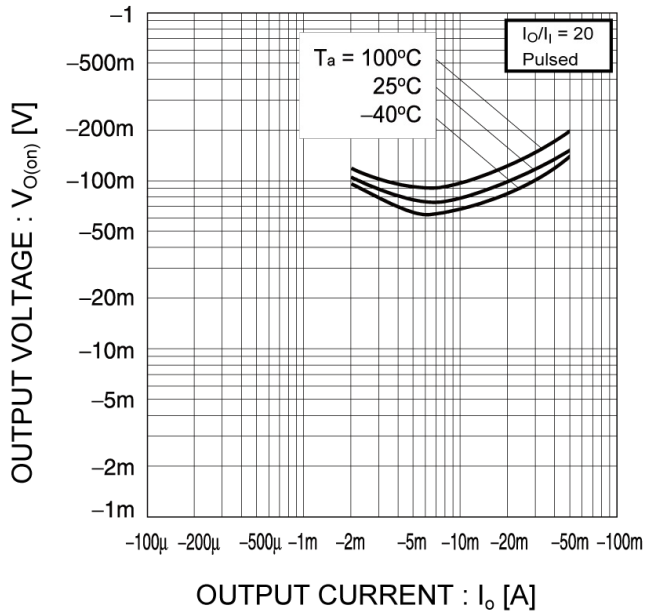


Fig.4 DC Current Gain vs. Output Current

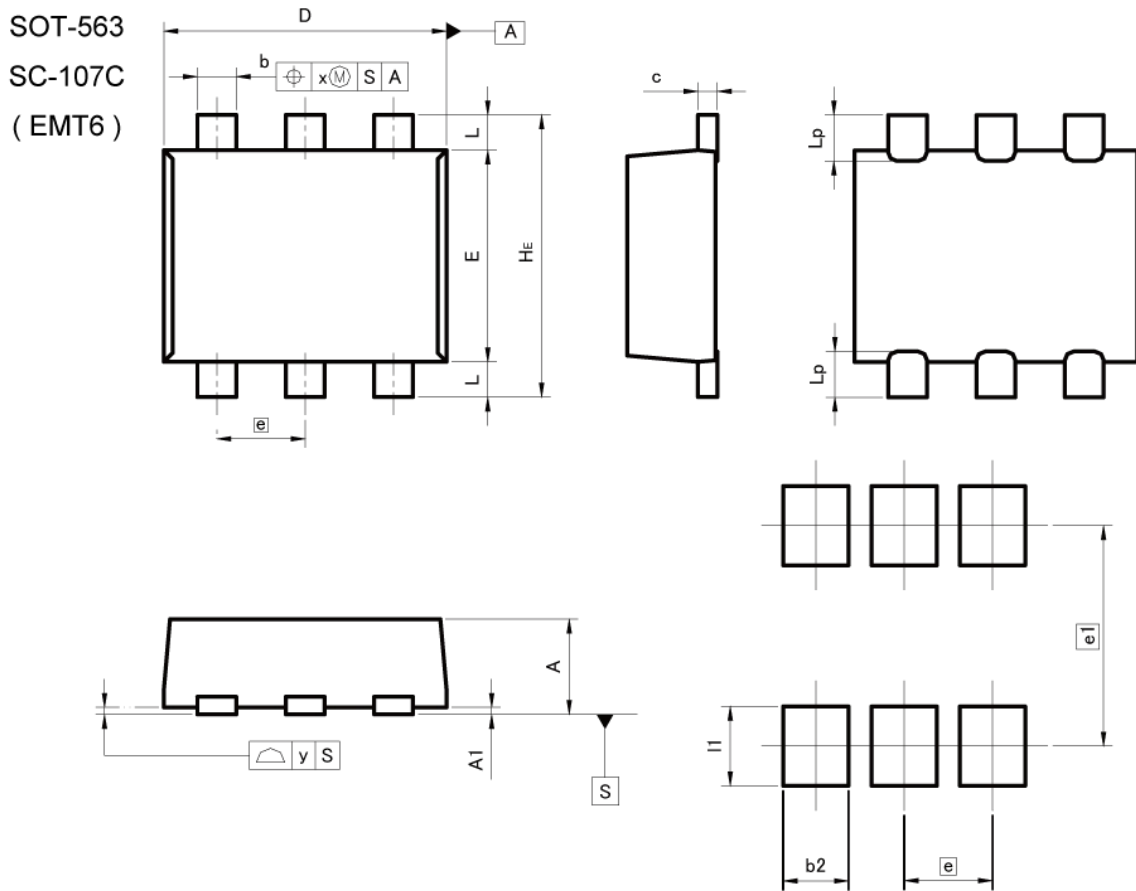


● Electrical characteristic curves ( $T_a=25^\circ\text{C}$ ) <For DTr2(PNP)>

Fig.5 Output Voltage vs. Output Current



●Dimensions



Pattern of terminal position areas  
[Not a pattern of soldering pads]

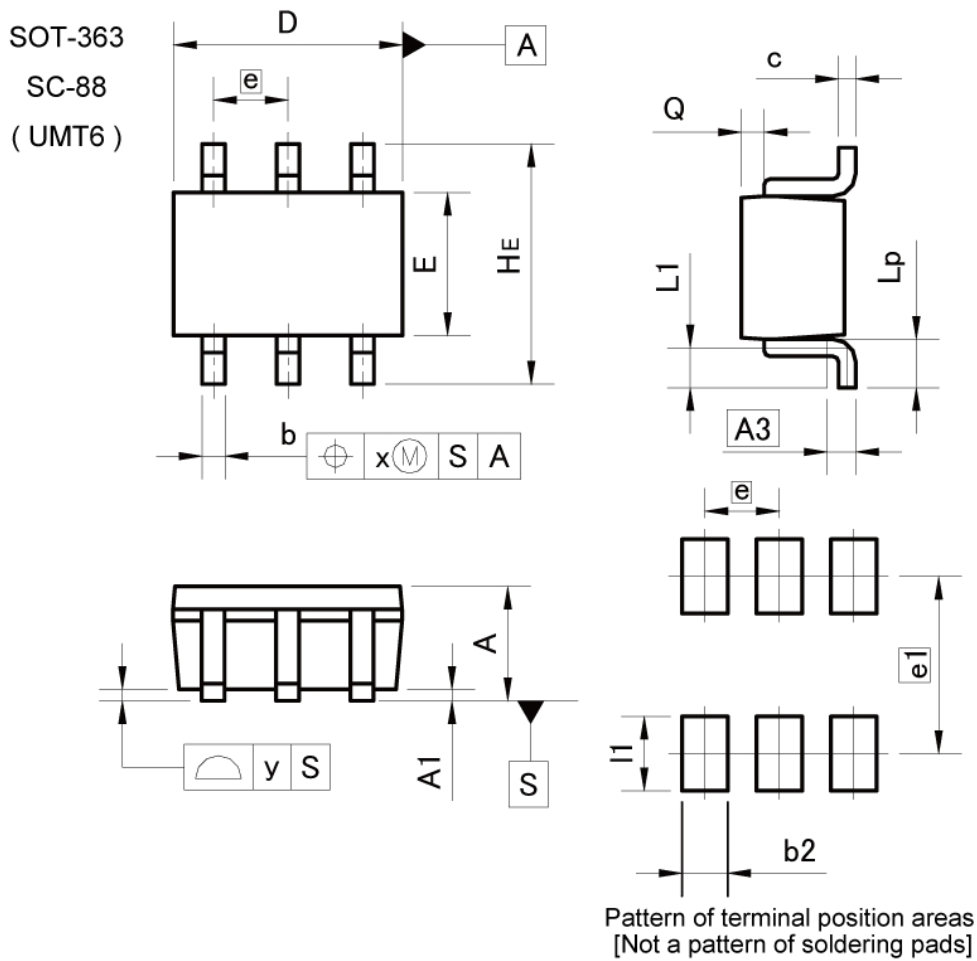
DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.45	0.55	0.018	0.022
A1	0.00	0.10	0.000	0.004
b	0.17	0.27	0.007	0.011
c	0.08	0.18	0.003	0.007
D	1.50	1.70	0.059	0.067
E	1.10	1.30	0.043	0.051
e	0.50		0.020	
HE	1.50	1.70	0.059	0.067
L	0.10	0.30	0.004	0.012
Lp	-	0.35	-	0.014
x	-	0.10	-	0.004
y	-	0.10	-	0.004

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
b2	-	0.37	-	0.015
e1	1.25		0.049	
I1	-	0.45	-	0.018

Dimension in mm/inches

●Dimensions



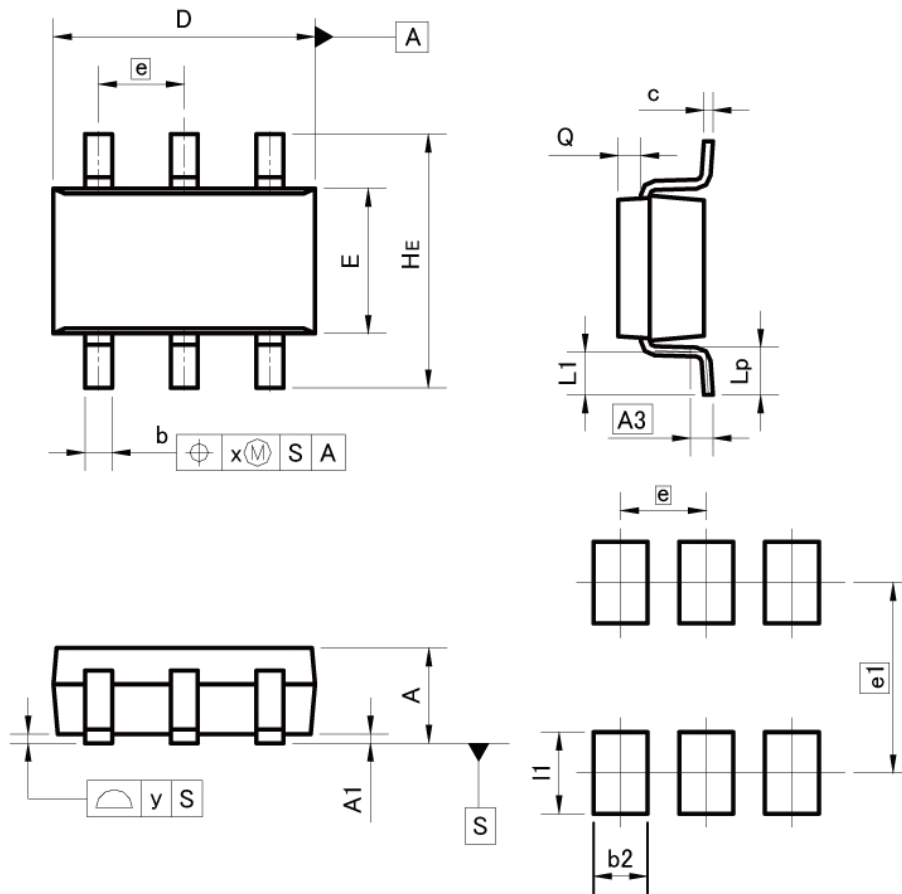
DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.80	1.00	0.031	0.039
A1	0.00	0.10	0.000	0.004
A3	0.25		0.010	
b	0.15	0.30	0.006	0.012
c	0.10	0.20	0.004	0.008
D	1.90	2.10	0.075	0.083
E	1.15	1.35	0.045	0.053
e	0.65		0.026	
HE	2.00	2.20	0.079	0.087
L1	0.20	0.50	0.008	0.020
Lp	0.25	0.55	0.010	0.022
Q	0.10	0.30	0.004	0.012
x	-	0.10	-	0.004
y	-	0.10	-	0.004

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
b2	-	0.40	-	0.016
e1	1.55		0.061	
I1	-	0.65	-	0.026

Dimension in mm/inches

●Dimensions

SOT-457  
 SC-74  
 (SMT6)



Pattern of terminal position areas  
 [Not a pattern of soldering pads]

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.00	1.30	0.039	0.051
A1	0.00	0.10	0.000	0.004
A3	0.25		0.010	
b	0.25	0.40	0.010	0.016
c	0.09	0.25	0.004	0.010
D	2.80	3.00	0.110	0.118
E	1.50	1.80	0.059	0.071
e	0.95		0.037	
HE	2.60	3.00	0.102	0.118
L1	0.30	0.60	0.012	0.024
Lp	0.40	0.70	0.016	0.028
Q	0.20	0.30	0.008	0.012
x	-	0.20	-	0.008
y	-	0.10	-	0.004

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
b2	-	0.60	-	0.024
e1	2.10		0.083	
I1	-	0.90	-	0.035

Dimension in mm/inches

# Notice

## Precaution on using ROHM Products

- Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment <sup>(Note 1)</sup>, transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

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JAPAN	USA	EU	CHINA
CLASS III	CLASS III	CLASS II b	CLASS III
CLASS IV		CLASS III	

- ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
  - Installation of protection circuits or other protective devices to improve system safety
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  - Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
  - Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - Sealing or coating our Products with resin or other coating materials
  - Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - Use of the Products in places subject to dew condensation
- The Products are not subject to radiation-proof design.
- Please verify and confirm characteristics of the final or mounted products in using the Products.
- In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

## Precaution for Mounting / Circuit board design

- When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

**Precautions Regarding Application Examples and External Circuits**

1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

**Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of Ionizer, friction prevention and temperature / humidity control).

**Precaution for Storage / Transportation**

1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

**Precaution for Product Label**

QR code printed on ROHM Products label is for ROHM's internal use only.

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When disposing Products please dispose them properly using an authorized industry waste company.

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